

ABSTRACT

A semiconductor device comprises a semiconductor IC chip provided with bond pads on its first surface, a wiring substrate provided with a through hole extending between the opposite surfaces thereof, conductive members electrically connecting the bond pads of the semiconductor IC chip to the conductive lines formed on the wiring substrate respectively, and a sealing resin coating coating the first surface of the semiconductor IC chip and the conductive members, and bonding the side surface of the semiconductor IC chip to the side surface of the through hole of the wiring substrate.